

LP-NSM020

Surface mount fuses

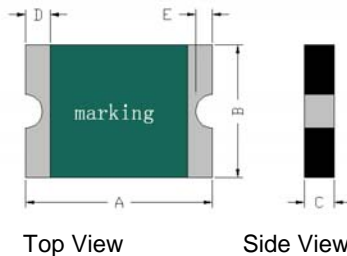
Features

- Small size of 1206
- Lead-free and compliant with the European Union RoHS Directive 2002/95/EC
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency Recognition: UL、CSA



Product Dimensions (mm)

Part number	A	B	C	D	E	Part marking
	Max.	Max.	Max.	Min.	Min.	
LP-NSM020	3.50	1.80	0.85	0.10	0.20	C

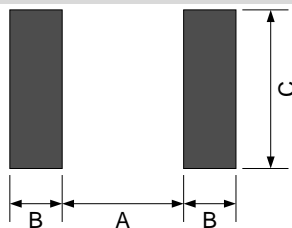


Electrical Characteristics

Part number	I _H	I _T	V _{max}	I _{max}	T _{trip}	Pd _{typ}	R _{min}	R _{1max}
	(A)	(A)	(V)	(A)	Current(A) Time(S)	(W)	(Ω)	(Ω)
LP-NSM020	0.20	0.40	16	40	8.0 0.05	0.6	0.60	2.50

I_H=Hold current: maximum current at which the device will not trip at 25°C still air.
I_T=Trip current: minimum current at which the device will always trip at 25°C still air.
V_{max}=Maximum voltage device can withstand without damage at rated current.
I_{max}=Maximum fault current device can withstand without damage at rated voltage.
T_{trip}=Maximum time to trip(s) at assigned current.
Pd_{typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.
R_{min}=Minimum device resistance at 25°C prior to tripping.
R_{1max}=Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A	B	C
	(mm)	(mm)	(mm)
LP-NSM020	1.80	1.00	1.80

* Recommended reflow methods: IR, Vapor phase, hot air oven.
* Devices can be cleaned using standard industry methods and solvents.

Notes:

- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- Devices are not designed to be wave soldered to the bottom side of the board.

Package Information

Tape & Reel: 4000pcs per reel.

Effectivity: Reference documents shall be the issue in effect on the date of invitation for bid.

Caution: Operation beyond the rated voltage or current may result in rupture electrical arcing or flame.

